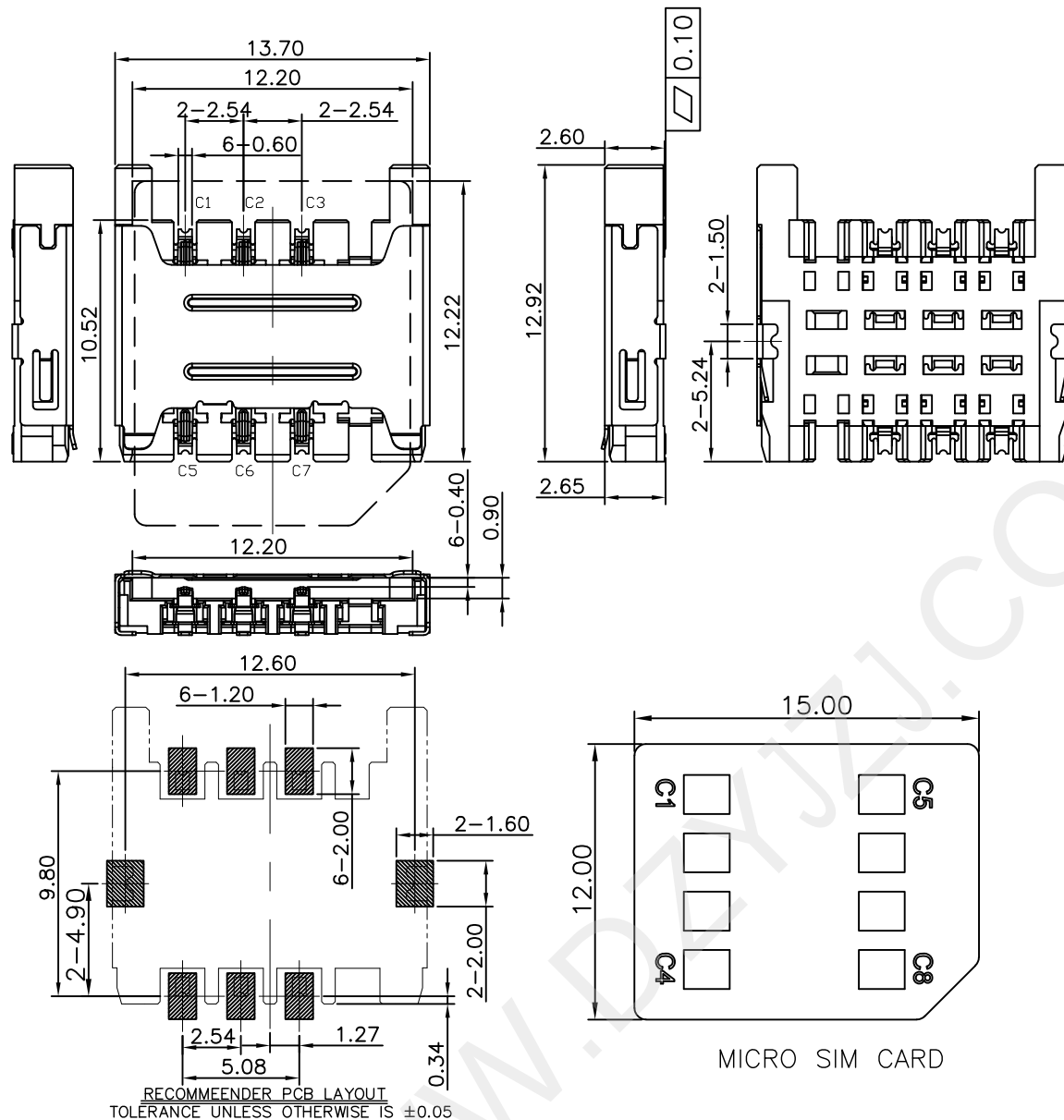


SIM Card Pin Assignments

NAND SIM CARD	
C1	Vcc
C2	RST
C3	CLK
C5	GND
C6	Vpp
C7	DATA

Name	Material	Electroplating
Plastic Housing	LCP Black	
Shell	SUS304 T=0.15	50μ" MIN NICKEL UNDERPLATED, GOLD FLASH PLATED SOLDER TAILS.
CONTACT Material	C5210R-EH T=0.12	50U" MIN NICKEL UNDERPLATED, 1U" MIN GOLD PLATED OVER ALL

NOTES :

1.Property:

- 1.1 Current Rating :1.0A AC/DC
- 1.2 Voltage Rating :50VRMS
- 1.3 Dielectric Withstanding Voltage: AC 500V r.m.s.
- 1.4 Insulation Resistance:1000MΩ minimum.
- 1.5 Contact Resistance:80mΩ maximum
- 1.6 Operating Temperature:-25°C~85°C



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ± 0.30 X.XX ± 0.25 X.XXX ± 0.15 X." ± 2 " X.X" ± 0.5 "	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: MICRO SIM CARD 6P 2.65H	
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC331-SIM06-265	MOLD NO.
 UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HYC-2211231224	SHEET NO. 1 OF 1